MANUAL DIE BONDER

T-3002-M

The **T-3002-M** is a manual, precise, high quality die bonder & component placer with superior ergonomic design and a fix die ejector needle. As with all of Tresky's products, the **T-3002-M** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height.

True Vertical Technology™

Unique pick-up from wafer

Easy to use

MICRO ASSEMBLY

T-3002-M

TRESKY

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Excellent performance, ergonomically designed and high reliability makes the T-3002-M ideal for small and medium production. Typically with a cycle time of approx. 5 sec. (process depending).

APPLICATIONS

Die Attach, Die Sorting, Flip-Chip, MEMS, MOEMS, VCSEL, Ultrasonic, Thermosonic, RFID, Adhesive Bonding, Eutectic Bonding (AuAu, ...), ...

FEATURES AND OPTIONS

Further Option: Flip-Chip Ultra

- **TRUE VERTICAL TECHNOLOGY™**
  Z-movement 95mm with 360° Tool rotation;
  Dispenser, Stamping, Ultrasonic, Scrub,Tool
  Heating, Pre Form Spindle, ...

- **XY placement stage supporting:**
  Waffle - / Gel - Pack -, Substrate - Holder,
  various Heating Plates

- **Pick-up from Wafer with Tresky's**
  die ejector system, especialy suitable
  for all kind of Si, GaAs and InP dies
  down to 30µm thickness.
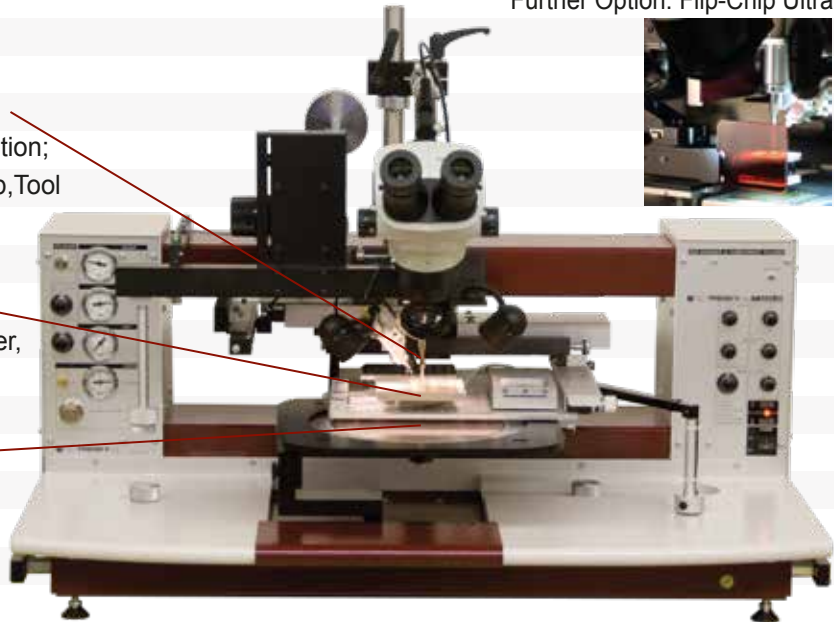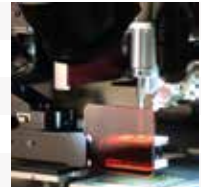
TECHNICAL DATA

XY- Movement (placement stage):	220mm x 220mm (manual)
XY- Movement (wafer stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360°
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	±10µm; ±5µm optional (process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

Represented by